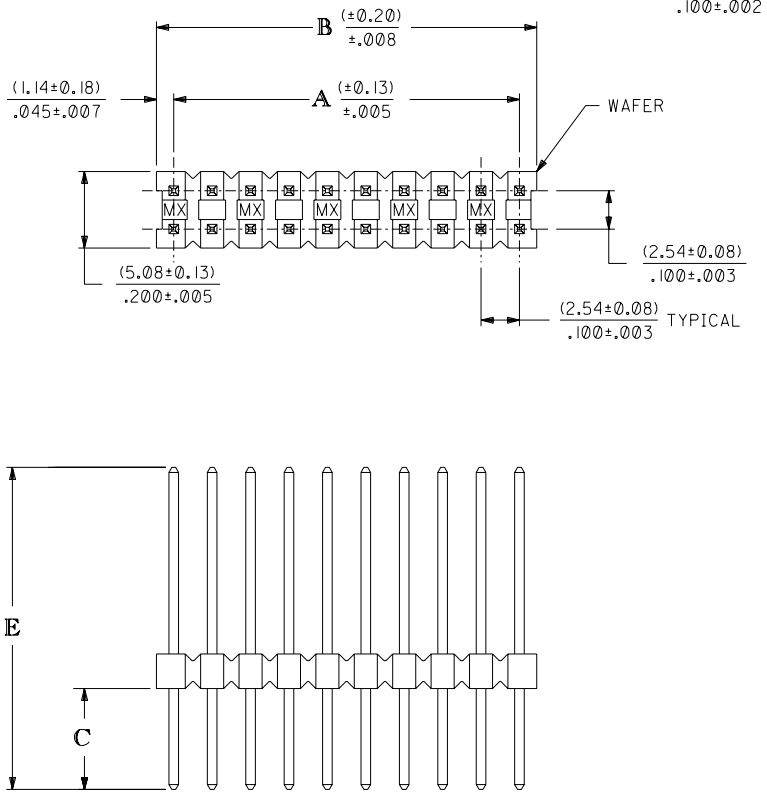
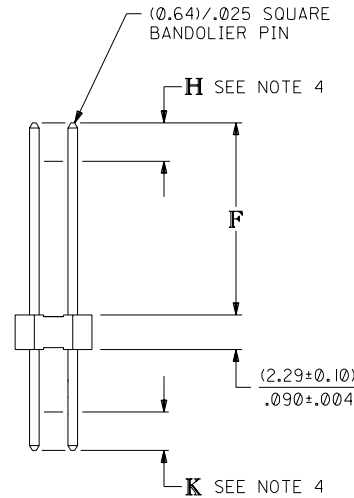




RECOMMENDED P.C. BOARD LAYOUT



NOTES:

- PIN PUSHOUT FORCE: 4 LBS. MINIMUM (IN EITHER DIRECTION)
- FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
- PINS MUST MEET MOLEX SOLDERABILITY SPECIFICATION ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE (APPROX. .025 LONG X .006 WIDE REF.- 2 LOCATIONS).
- MEASURE POINT FOR PLATING THICKNESS.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-8624.
- PACKAGING INFORMATION:
(UNLESS OTHERWISE NOTED IN TABLES)
PER PACKAGING DRAWING NO. PK-70873-0353
BULK PACKAGED IN BAGS

MATERIAL:

WAFER - GLASS FILLED POLYESTER; UL94V-0; COLOR: BLACK
PIN - PHOSPHOR BRONZE

PLATING:

- TIN - .000150 MINIMUM TIN PLATE OVER .000050 MINIMUM NICKEL PLATE.
- 15 GOLD - .000015 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER .000050 MINIMUM NICKEL PLATE OVERALL.
- 30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER .000050 MINIMUM NICKEL PLATE OVERALL.
- D30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREAS OVER .000050 MINIMUM NICKEL PLATE OVERALL.
- 5 GOLD - .000005 MINIMUM GOLD FLASH IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER .000050 MINIMUM NICKEL PLATE OVERALL.

*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

CKT. SIZE	DIMENSION A		DIMENSION B	
	(MM)	INCH	(MM)	INCH
4	(2.54)	.100	(4.83)	.190
6	(5.08)	.200	(7.37)	.290
8	(7.62)	.300	(9.91)	.390
10	(10.16)	.400	(12.45)	.490
12	(12.70)	.500	(14.99)	.590
14	(15.24)	.600	(17.53)	.690
16	(17.78)	.700	(20.07)	.790
18	(20.32)	.800	(22.61)	.890
20	(22.86)	.900	(25.15)	.990
22	(25.40)	1.000	(27.69)	1.090
24	(27.94)	1.100	(30.23)	1.190
26	(30.48)	1.200	(32.77)	1.290
28	(33.02)	1.300	(35.31)	1.390
30	(35.56)	1.400	(37.85)	1.490
32	(38.10)	1.500	(40.39)	1.590
34	(40.64)	1.600	(42.93)	1.690
36	(43.18)	1.700	(45.47)	1.790
38	(45.72)	1.800	(48.01)	1.890
40	(48.26)	1.900	(50.55)	1.990
42	(50.80)	2.000	(53.09)	2.090
44	(53.34)	2.100	(55.63)	2.190
46	(55.88)	2.200	(58.17)	2.290
48	(58.42)	2.300	(60.71)	2.390
50	(60.96)	2.400	(63.25)	2.490
52	(63.50)	2.500	(65.79)	2.590
54	(66.04)	2.600	(68.33)	2.690
56	(68.58)	2.700	(70.87)	2.790
58	(71.12)	2.800	(73.41)	2.890
60	(73.66)	2.900	(75.95)	2.990
62	(76.20)	3.000	(78.49)	3.090
64	(78.74)	3.100	(81.03)	3.190
66	(81.28)	3.200	(83.57)	3.290
68	(83.82)	3.300	(86.11)	3.390
70	(86.36)	3.400	(88.65)	3.490
72	(88.90)	3.500	(91.19)	3.590
74	(91.44)	3.600	(93.73)	3.690
76	(93.98)	3.700	(96.27)	3.790
78	(96.52)	3.800	(98.81)	3.890
80	(99.06)	3.900	(101.35)	3.990

DIMENSIONS SHOWN (METRIC) INCH		UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
INCH		METRIC	
3 PLACE ± .005			
2 PLACE ± .01	± 0.13		
1 PLACE ± .025	± 0.25		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY: EIK	CHK'D. BY: AAB		
APPR'D. BY: WAZ	SCALE: 4 : 1		
FILE NAME: 58624X1		SHEET NO. 1 OF 7	
DATE: 11/30/88		DATE: 11/30/88	
SALES ASSY-DUAL ROW WAFER W/BREAK-OFF OPTION .025 SQ. PINS/.100 GRID			
MOLEX INCORPORATED			
SEE CHARTS SDA-8624-0001-5000			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

I3		I2		I1		I0		9		8		7		6		8624		4		3		2		1			
ENGINEERING NUMBER A-8624		RELEASE FOR MANUFACTURE						C ± (0.38) .015		E ± (0.25) .010		F ± (0.25) .010				CONNECTOR END PLATING		P.C. BOARD END PLATING				FOR PACKAGING INFORMATION, SEE NOTE 6, SHEET 1 (UNLESS OTHERWISE SPECIFIED BELOW)					
								(4.70) .185		(15.11) .595		(8.13) .320				30 GOLD		GOLD		(4.57) .180		TIN		(1.27) .050			
								(2.72) .107		(11.10) .437		(6.10) .240				5 GOLD		GOLD		(2.54) .100		TIN		(1.27) .050			
								(5.64) .222		(15.75) .620		(7.82) .308				TIN		TIN		(2.54) .100		TIN		(1.27) .050			
								(0.56) .022 MAX.		(13.21) .520		(10.67) .420 ± (0.13) .005				TIN		TIN		(2.54) .100		N/A		N/A N/A		PK-70873-0688 ALL CIRCUIT SIZES	